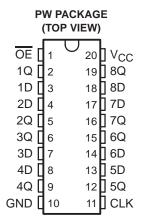
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- **Controlled Baseline**
 - One Assembly/Test Site, One Fabrication
- **Extended Temperature Performance of** -40°C to 105°C
- **Enhanced Diminishing Manufacturing** Sources (DMS) Support
- **Enhanced Product-Change Notification**
- Qualification Pedigree†
- Typical V_{OI P} (Output Ground Bounce) <0.8 V at $V_{CC} = 3.3 \text{ V}, T_A = 25^{\circ}\text{C}$
- Typical V_{OHV} (Output V_{OH} Undershoot) $>2.3 \text{ V at V}_{CC} = 3.3 \text{ V}, T_A = 25^{\circ}\text{C}$
- **Supports Mixed-Mode Voltage Operation on All Ports**
- † Component qualification in accordance with JEDEC and industry standards to ensure reliable operation over an extended temperature range. This includes, but is not limited to, Highly Accelerated Stress Test (HAST) or biased 85/85, temperature cycle, autoclave or unbiased HAST, electromigration, bond intermetallic life, and mold compound life. Such qualification testing should not be viewed as justifying use of this component beyond specified performance and environmental limits.

- Ioff Supports Partial-Power-Down Mode Operation
- **ESD Protection Exceeds JESD 22**
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)



description/ordering information

The SN74LV374A is an octal edge-triggered D-type flip-flop designed for 2-V to 5.5-V V_{CC} operation.

This device features 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. It is particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

On the positive transition of the clock (CLK) input, the Q outputs are set to the logic levels set up at the data (D) inputs.

A buffered output-enable (\overline{OE}) input can be used to place the eight outputs in either a normal logic state (high or low logic levels) or high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and the increased drive provide the capability to drive bus lines without need for interface or pullup components.

OE does not affect internal operations of the latch. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

ORDERING INFORMATION

TA	PACK	AGE‡	ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 105°C	TSSOP - PW	Tape and reel	SN74LV374ATPWREP	LV374AEP

[‡]Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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description/ordering information (continued)

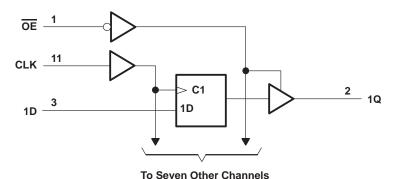
To ensure the high-impedance state during power up or power down, $\overline{\sf OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

This device is fully specified for partial-power-down applications using I_{off}. The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

FUNCTION TABLE (each flip-flop)

	INPUTS	OUTPUT	
OE	CLK	D	Q
L	↑	Н	Н
L	\uparrow	L	L
L	L	Χ	Q_0
Н	X	Χ	Z

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage range, V _{CC}	0.5 V to 7 V
Input voltage range, V _I (see Note 1)	–0.5 V to 7 V
Voltage range applied to any output in the high-impedance or	
power-off state, V _O (see Note 1)	–0.5 V to 7 V
Output voltage range, V _O (see Notes 1 and 2)	0.5 V to V _{CC} + 0.5 V
Input clamp current, I_{IK} ($V_I < 0$)	–20 mA
Output clamp current, I _{OK} (V _O < 0)	–50 mA
Continuous output current, $I_O(V_O = 0 \text{ to } V_{CC})$	±35 mA
Continuous current through V _{CC} or GND	±70 mA
Package thermal impedance, θ _{JA} (see Note 3)	83°C/W
Storage temperature range, T _{stq}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.
 - 2. This value is limited to 5.5 V maximum.
 - 3. The package thermal impedance is calculated in accordance with JESD 51-7.



recommended operating conditions (see Note 4)

			MIN	MAX	UNIT	
Vcc	Supply voltage		2	5.5	V	
		V _{CC} = 2 V	1.5			
.,	High level input valte me	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	V _{CC} ×0.7		V	
V_{IH}	High-level input voltage	$V_{CC} = 3 \text{ V to } 3.6 \text{ V}$	V _{CC} ×0.7		V	
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$	V _{CC} ×0.7			
		V _{CC} = 2 V		0.5		
V/	Law laval input valtage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		$V_{CC} \times 0.3$	V	
V_{IL}	Low-level input voltage	$V_{CC} = 3 \text{ V to } 3.6 \text{ V}$		$V_{CC} \times 0.3$	V	
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$		$VCC \times 0.3$		
٧ _I	Input voltage		0	5.5	V	
\/ -	Output valle ve	High or low state	0	VCC	٧	
VO	Output voltage	3-state	0	5.5	V	
		V _{CC} = 2 V		-50	μΑ	
	IPak land adad amad	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		-2		
ЮН	High-level output current	$V_{CC} = 3 \text{ V to } 3.6 \text{ V}$		-8	mA	
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$		-16		
		V _{CC} = 2 V		50	μΑ	
1	Laur laural autaut aussaut	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		2		
lOL	Low-level output current	$V_{CC} = 3 \text{ V to } 3.6 \text{ V}$		8	mA	
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$		16		
		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		200		
$\Delta t/\Delta v$	Input transition rise or fall rate	$V_{CC} = 3 \text{ V to } 3.6 \text{ V}$		100	ns/V	
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$		20		
TA	Operating free-air temperature		-40	105	°C	

NOTE 4: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{CC}	MIN	TYP	MAX	UNIT
	I _{OH} = -50 μA	2 V to 5.5 V	V _{CC} -0.1			
	I _{OH} = -2 mA	2.3 V	2			.,
VOH	I _{OH} = -8 mA	3 V	2.48			V
	I _{OH} = -16 mA	4.5 V	3.8			
	I _{OL} = 50 μA	2 V to 5.5 V			0.1	
.,	I _{OL} = 2 mA	2.3 V			0.4	.,
VOL	I _{OL} = 8 mA	3 V			0.44	V
	I _{OL} = 16 mA	4.5 V			0.55	
Ц	V _I = 5.5 V or GND	0 to 5.5 V			±1	μΑ
loz	$V_O = V_{CC}$ or GND	5.5 V			±5	μΑ
Icc	$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V			20	μΑ
loff	V_I or $V_O = 0$ to 5.5 V	0			5	μΑ
Ci	V _I = V _{CC} or GND	3.3 V		2.9		pF



SN74LV374A-EP OCTAL EDGE-TRIGGERED D-TYPE FLIP-FLOP WITH 3-STATE OUTPUTS

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timing requirements over recommended operating free-air temperature range, V_{CC} = 3.3 V \pm 0.3 V (unless otherwise noted) (see Figure 1)

		$T_A = 2$	25°C		MAN	
		MIN MAX		MIN	MAX	UNIT
t _W	Pulse duration, CLK high or low	5		5.5		ns
t _{su}	Setup time, data before CLK↑	4.5		4.5		ns
th	Hold time, data after CLK↑	2	·	2	·	ns

timing requirements over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

		T _A = 2	25°C	MIN	MAY	LINUT
		MIN	MAX	IVIIN IVIA	MAX	UNIT
t _W	Pulse duration, CLK high or low	5		5		ns
t _{su}	Setup time, data before CLK↑	3		3		ns
th	Hold time, data after CLK↑	2		2		ns

switching characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V \pm 0.3 V (unless otherwise noted) (see Figure 1)

DADAMETED	FROM	то	LOAD	T,	Վ = 25° C	;	BAINI	BA A V	LINUT
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN	MAX	UNIT
f _{max}				55	110		50		MHz
^t pd	CLK	Q			8.3	16.2	1	18.5	
t _{en}	ŌĒ	Q	C _L = 50 pF		7.7	14.5	1	17.5	
^t dis	ŌĒ	Q			5.9	14	1	16	ns
t _{sk(o)}						1.5			

switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

DADAMETED	FROM	то	LOAD	T,	4 = 25°C	;	BAINI	14 A V	
PARAMETER	(INPUT)	(OUTPUT)	CAPACITANCE	MIN	TYP	MAX	MIN	MAX	UNIT
f _{max}				85	170		75		MHz
t _{pd}	CLK	Q			5.9	10.1	1	13.5	
t _{en}	ŌĒ	Q	C _L = 50 pF		5.5	9.6	1	13	
^t dis	ŌĒ	Q]		4	8.8	1	10	ns
tsk(o)						1			

SN74LV374A-EP **OCTAL EDGE-TRIGGERED D-TYPE FLIP-FLOP** WITH 3-STATE OUTPUTS SCLS500A - MAY 2003 - REVISED MAY 2004

noise characteristics, V_{CC} = 3.3 V, C_L = 50 pF, T_A = 25°C (see Note 5)

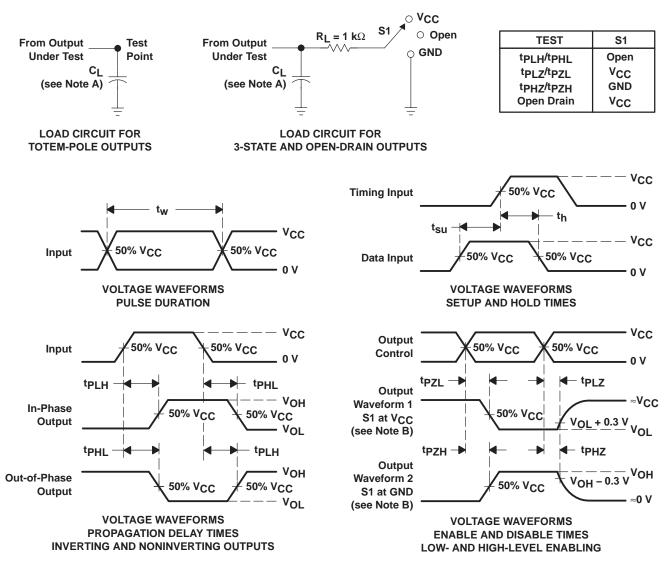
	PARAMETER	MIN	TYP	MAX	UNIT
V _{OL(P)}	Quiet output, maximum dynamic V _{OL}		0.6	0.8	V
V _{OL(V)}	Quiet output, minimum dynamic V _{OL}		-0.5	-0.8	V
VOH(V)	Quiet output, minimum dynamic VOH		2.9		V
VIH(D)	High-level dynamic input voltage	2.31			V
V _{IL(D)}	Low-level dynamic input voltage			0.99	V

NOTE 5: Characteristics are for surface-mount packages only.

operating characteristics, $T_A = 25^{\circ}C$

	PARAMETER	TEST CO	VCC	TYP	UNIT	
C _{pd} Power dissipation capacitance	Outpute enabled	C. F0 pF	f 40 MH=	3.3 V	21.1	
	Power dissipation capacitance	Outputs enabled	$C_L = 50 pF$,	f = 10 MHz	5 V	22.8

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_I includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- All input pulses are supplied by generators having the following characteristics: $PRR \le 1 \text{ MHz}$, $Z_O = 50 \Omega$, $t_f \le 3 \text{ ns}$, $t_f \le 3 \text{ ns}$.
- D. The outputs are measured one at a time, with one input transition per measurement.
- E. tpl 7 and tpH7 are the same as tdis.
- F. tpzi and tpzH are the same as ten.
- G. tpHL and tpLH are the same as tpd.
- H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms





PACKAGE OPTION ADDENDUM

10-Dec-2020

PACKAGING INFORMATION

www.ti.com

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SN74LV374ATPWREP	ACTIVE	TSSOP	PW	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 105	LV374AEP	Samples
V62/03663-01XE	ACTIVE	TSSOP	PW	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 105	LV374AEP	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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PACKAGE OPTION ADDENDUM

10-Dec-2020

OTHER QUALIFIED VERSIONS OF SN74LV374A-EP:

• Automotive: SN74LV374A-Q1

NOTE: Qualified Version Definitions:

• Catalog - TI's standard catalog product

• Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects

PACKAGE MATERIALS INFORMATION

www.ti.com 3-Jun-2022

TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	_	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LV374ATPWREP	TSSOP	PW	20	2000	330.0	16.4	6.95	7.0	1.4	8.0	16.0	Q1

PACKAGE MATERIALS INFORMATION

www.ti.com 3-Jun-2022



*All dimensions are nominal

	Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)	
ı	SN74LV374ATPWREP	TSSOP	PW	20	2000	356.0	356.0	35.0	

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